	Material Compo © Copyright 2005. If international and Pan	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	tion of the tion o	he substance asses all low	s within the er level mat	manufactur erials for wl	er listed it hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with low responsibility.	
752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	ials and Mfg Information				
upplie	r Information															
Company name*				Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-05-10				
ontact N	lame	Title - Contact			]	Phone - Contact*					Email - Contact*					
Product-	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*						
roduct-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item Nu   BYW29-200		n Number Mfr Item Name			·	Effective Date	e Vers	Version Manufacturing Site		ring Site	V	Veight*	UOM	Unit Type	
			-200G	G REC T0220 8A 200V ULTFST			2024-05-10 CN5			1	962.01	mg	Each			
Ianufa	cturing Proccess Informat	tion												I		
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 I		-STD-020 MSI	L Rating	Peak Process Body Temperat		ure Max Time at Peak Ten		Temperate	are Numb	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ls 3						
omments	3															
or more	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	А	Lead (Pb)	7439-92-1	7a	74.682	mg
			Supplier	Tin (Sn)	7440-31-5		8.298	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9	mg		Metal Hydroxide	proprietary data		38.073	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.925	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		81.585	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		13.5975	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted)